

~ Clean type solder paste ~



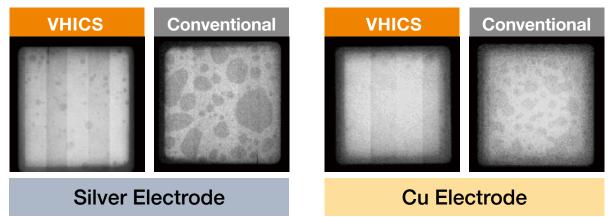
Low void generation of heatsink heat radiation bottom electrode, has superior residue cleaning characteristics

Characteristics

- Regardless of electrode, low void generation of bottom electrode
- No alteration of flux after reflow heating, offers superior cleaning performance
- Controls solder or flux spattering in reflow

Void

Void generation was controlled by choosing active agent suitable for electrode

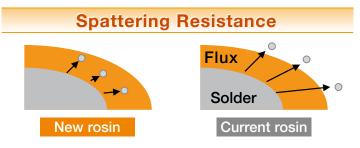


Cleaning · Spattering Characteristics

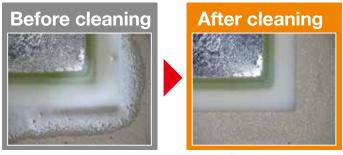
- Control spattering by using strong adhesion rosin
- Use of newly developed rosin with superior heat resistance and strong adhesion performance



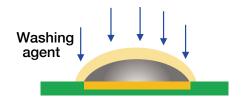




Cleaning characteristics



«Cleaning solution, Clean though 750HS (by Kao Corporation)



Use of heat resistance rosin prevents oxidation, provides excellent cleaning performance